Check for updates

Journal of Electronic Packaging

Editorial

Letter From the Editors

Greetings from Professor Bahgat G. Sammakia of Binghamton University (Editor from 2004 to 2014) and Professor Y. C. Lee of the University of Colorado Boulder (Editor from 2014 to 2019). We would like to express our appreciation to all the authors, reviewers, guest editors, and associate editors (AE) for their outstanding contributions. We would also like to thank our readers who have played an essential role in the stimulating process regarding the generation and dissemination of knowledge in the area of electronic packaging.

During the last ten years, it was a great pleasure working with the many outstanding AEs who served the JEP, the ASME staff, and with Mr. Gary Miller. Thanks to all of us working as a team, we were able to get the JEP to significantly reduce the time to publication. We were able to increase the impact factor, and we were able to reduce the acceptance rate to below 50%. We have also established an annual *Best Paper of the Year Award, Best AE of the Year Award, and Best Reviewer(s) of the Year Award*. We have started a series of special issues which highlight areas of general interest to the technical community, and we endeavored to select topics that are current, interesting, and likely to attract readership, subscriptions, and contributions.

For the next 5 years, we plan to enhance the journal's impact further. We will make sure the review process will be timely, fair, and effective in order to publish high quality articles with impact that may be appreciated in 2 years or in 10 or 20 years after publication. We will publish review articles in each issue to cover hot, emerging, and fundamental topics. These review articles will enhance service to our regular readers and reach out to many other prospective readers. Electronic packaging is essential for a wide spectrum of applications represented by smartphones/tablets/wearable electronics, computers, data centers, wireless/photonic communication, sensors/actuators, biomedical devices, energy systems, and military systems. The electronic packaging community is expanding fast, corresponding to the impressive growth of packaging's design and manufacturing activities. We want to make sure the *ASME Journal of Electronic Packaging* continues its leadership to serve the community. In addition to journal publications, we plan to establish a professional network with associated web pages. Every one of our readers is welcome to participate in such a network. If you want to participate or give us your feedback, feel free to send us an email at asmejep@gmail.com.

We thank you for your past support and look forward to working with you in the years to come.

Sincerely,

Bahgat G. Sammakia and Y. C. Lee
September 1, 2014

Downloaded from http://energyresources.asmedigitalcollection.asme.org/electronicpackaging/article-pdf/136/3/030201/6394114/ep_136_03_030201.pdf by guest on 08 October 2024

 Copyright © 2014 by ASME